HOSTAFORM® C 2521 G

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Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNS, 01-001 POM copolymer Stiff-flowing type for injection molding and extrusion, modified with (R) GUR (PE-UHMW); good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation; very good lubricating properties. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm. Ranges of applications: For injection molding parts and semi-finished products with higher requirements on lubricating properties. FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	1.5	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	

Typical mechanical properties

Tensile modulus	2100	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	44	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	12	%	ISO 527-1/-2
Nominal strain at break	15	%	ISO 527-1/-2
Flexural modulus	2000	MPa	ISO 178
Tensile creep modulus, 1h	1800	MPa	ISO 899-1
Tensile creep modulus, 1000h	1000	MPa	ISO 899-1
Charpy impact strength, 23°C	50	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	50	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	4.5	kJ/m^2	ISO 179/1eA
Ball indentation hardness, H 358/30	110	MPa	ISO 2039-1
Poisson's ratio	0.4[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	165	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	84	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	100	E-6/K	ISO 11359-1/-2

Electrical properties

Relative permittivity, 100Hz	3.8		IEC 62631-2-1
Relative permittivity, 1MHz	3.8		IEC 62631-2-1
Dissipation factor, 100Hz	20	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	70	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	35	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112

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Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.8	%	Sim. to ISO 62
Density	1340	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing	Injection Moulding, Film Extrusion, Extrusion, Sheet Extrusion, Other Extrusion, Blow Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low wear / Low friction

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Film extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Other extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Profile extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Sheet extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

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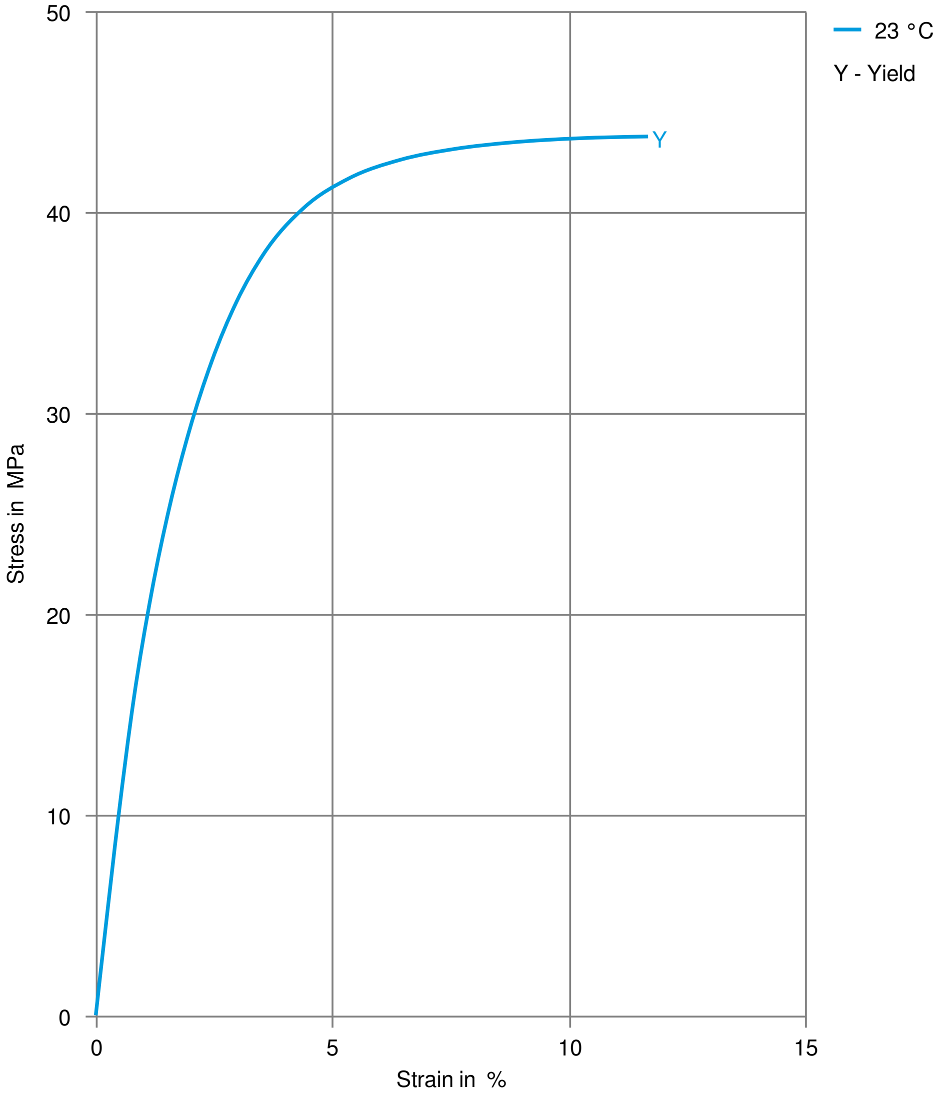
Stress-strain



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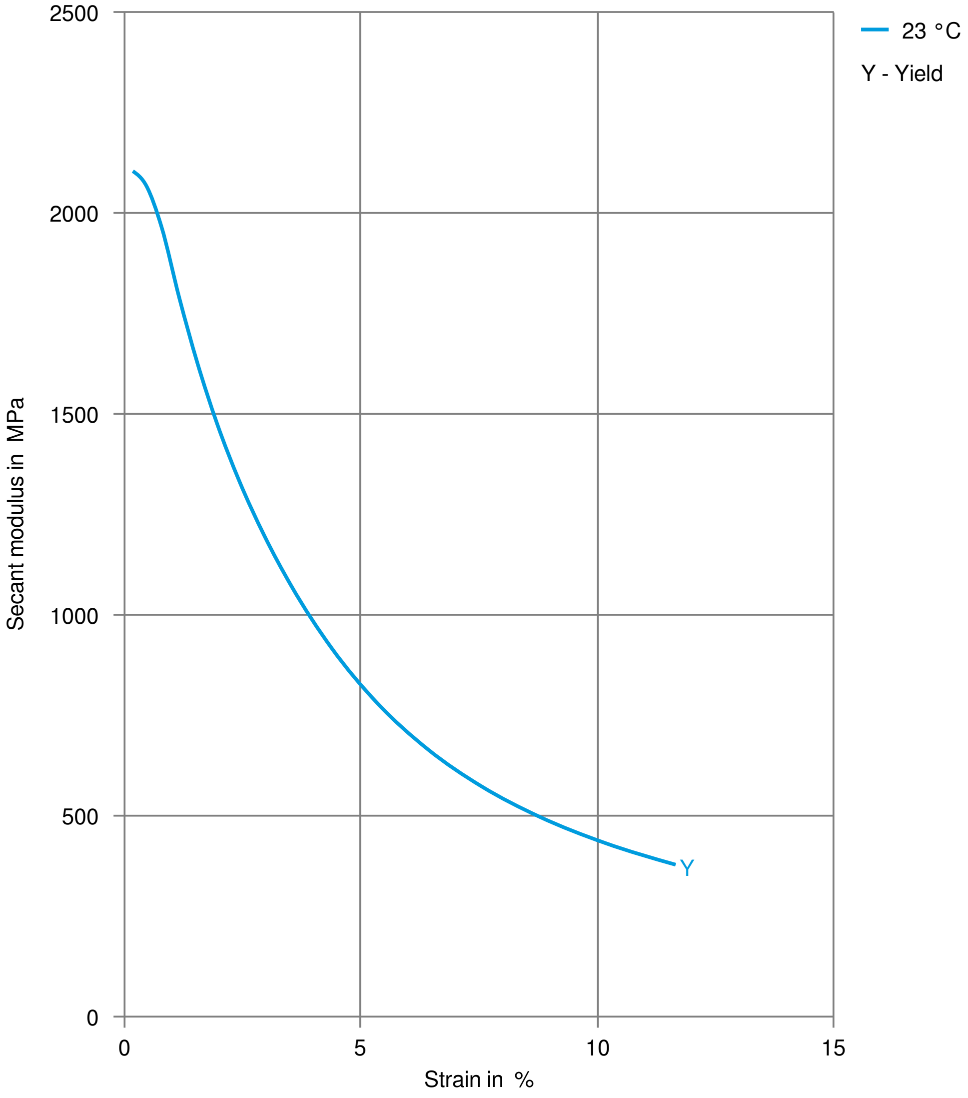
Secant modulus-strain



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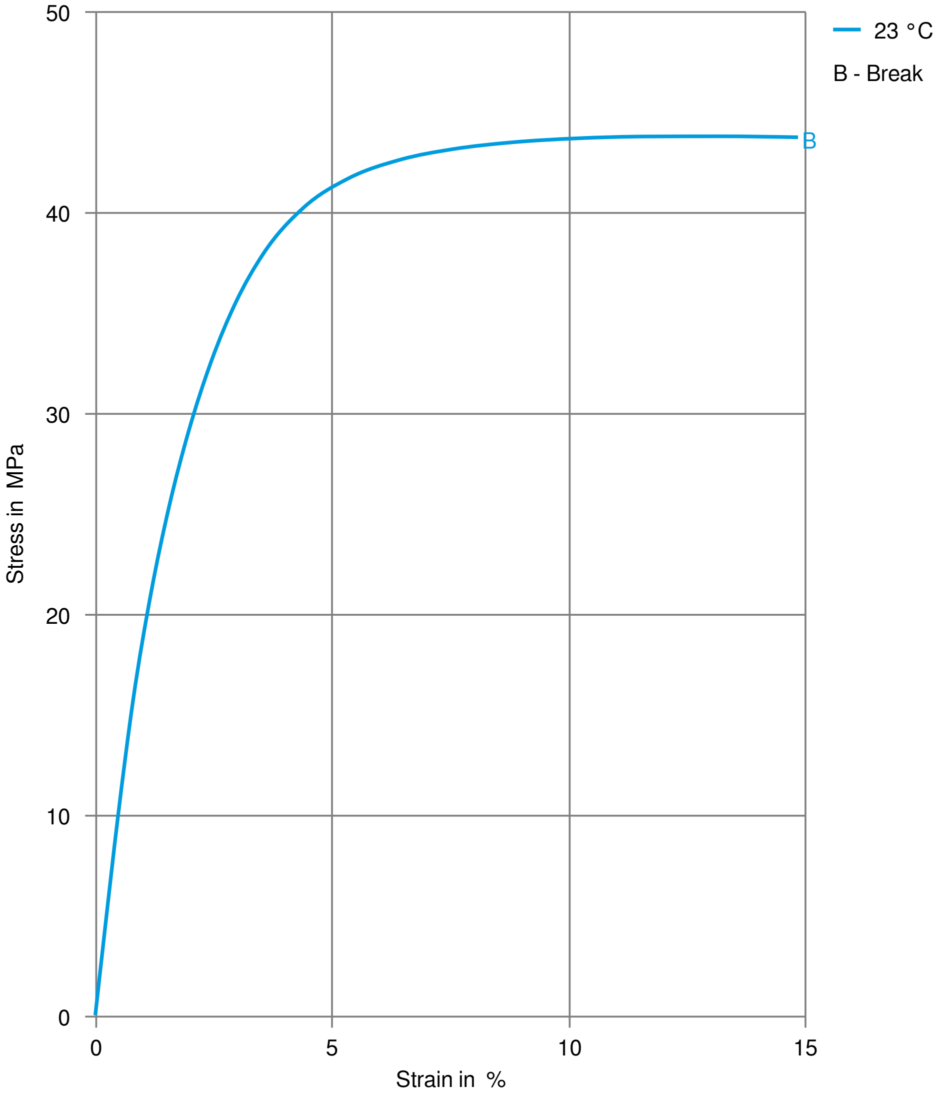
Stress-strain, 50mm/min



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Secant modulus-strain, 50mm/min